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journal homepage: www.elsevier.com/locate/jeurceramsocAlN with high strength and high thermal conductivity based on an MCAS-Y₂O₃-YSZ multi-additive systemSu-Hyun Baek^{a,b}, Hyeondeok Jeong^{a,*}, Sung-Soo Ryu^{a,*}^a Engineering Ceramic Center, Korea Institute of Ceramic Engineering and Technology, Icheon, 17303, Republic of Korea^b Department of Molecular and Material Sciences, Interdisciplinary Graduate School of Engineering Sciences, Kyushu University, 6-1 Kasuga-koen, Kasuga-Shi, Fukuoka, 816-8580, Japan

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ABSTRACT

The additive composition of an AlN ceramic substrate material was optimized to achieve high strength and thermal conductivity. MgO-CaO-Al₂O₃-SiO₂ (MCAS) glass and Y₂O₃ were used as basic additives for improved sintering properties and thermal conductivity, thereby allowing for AlN to be sintered at a relatively low temperature of 1600 °C without pressurization. Yttria-stabilized zirconia (YSZ) was added (0–3 wt%) to further improve the strength of the AlN ceramic. YSZ and Y₂O₃ reacted with AlN to produce ZrN, Y₄Al₂O₉, and Y₃Al₅O₁₂ secondary phases. The formation of these yttrium aluminate phases improved the thermal conductivity by removing oxygen impurities, while ZrN formed at the AlN grain boundaries provided resistance to grain boundary fractures for improved strength. Overall, the AlN ceramic with 1 wt% MCAS, 3 wt% Y₂O₃, and 1 wt% YSZ exhibited excellent thermal and mechanical properties, including a thermal conductivity of 109 W/mK and flexural strength of 608 MPa.

1. Introduction

The growing popularity of electric transportation vehicles (e.g., automobiles and aircraft) has led to rapid growth in the demand for electric devices (e.g., power modules) and related materials. Ceramic substrate materials are commonly used in power modules, as they offer excellent electrical insulation and thermal shock resistance against the heat generated by the electrical resistance of the circuit during power consumption. Further, high thermal conductivity and mechanical strength are required. Common ceramic substrate materials include aluminum oxide (Al₂O₃), zirconia-toughened alumina (ZTA), aluminum nitride (AlN), and silicon nitride (Si₃N₄). Al₂O₃ is associated with both low thermal conductivity and low strength, while ZTA offers high strength but low thermal conductivity. Further, Si₃N₄ offers excellent properties, but commercialization remains a challenge due to difficulties associated with the production of synthetic and sintered products. Alternatively, AlN is a promising heat dissipating and electrically insulating material that offers high thermal conductivity, and is relatively easy to produce [1–7]. However, AlN has a relatively low mechanical strength of 300–400 MPa.

Various studies have investigated the use of additives and heat treatment to improve the strength characteristics of AlN [8–12]. Lee et al. reported that the addition of CaZrO₃ to AlN led to intergranular pinning of the secondary phases, thereby facilitating a high flexural strength of 560 MPa [8]. Further, Kusunose et al. and Zhan et al. produced high strength AlN without compromising its high thermal conductivity by controlling the grain growth after low-temperature sintering using CeO₂ and SmO₂-CaO additives, respectively [9,10]. Liu et al. reported that the fracture mode at the grain boundaries of AlN was changed to intragranular fracture using Si₃N₄ as an additive, which led to increased hardness and strength [11].

Meanwhile, glass-based oxides have also been considered as additives to enhance the sinterability of AlN [13–15]. For example, Lee et al. reported that sintered bodies with a density close to theoretical density were obtained, and a thermal conductivity of 84 W/mK was attained via unpressured sintering for 1 h at 1600 °C with 1 wt% MgO-CaO-Al₂O₃-SiO₂ (MCAS) glass oxide additive-doped AlN [14]. Although the study of mechanical strength has not been conducted, this finding suggested that the mechanical properties of AlN can be improved by controlling the microstructure via lower temperature sintering.

Abbreviations: BEI, backscattered electron imaging; PET, polyethylene terephthalate; SEM, scanning electron microscopy; TEM, transmission electron microscopy; XRD, X-ray diffraction; YSZ, yttria-stabilized zirconia; ZTA, zirconia-toughened alumina.

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